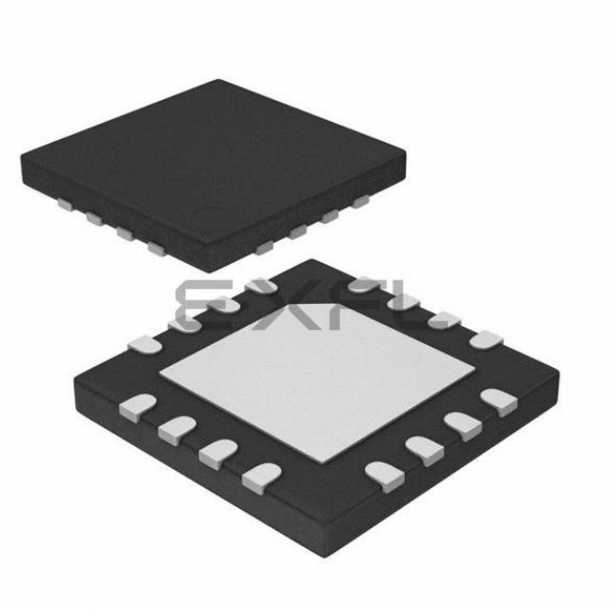

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

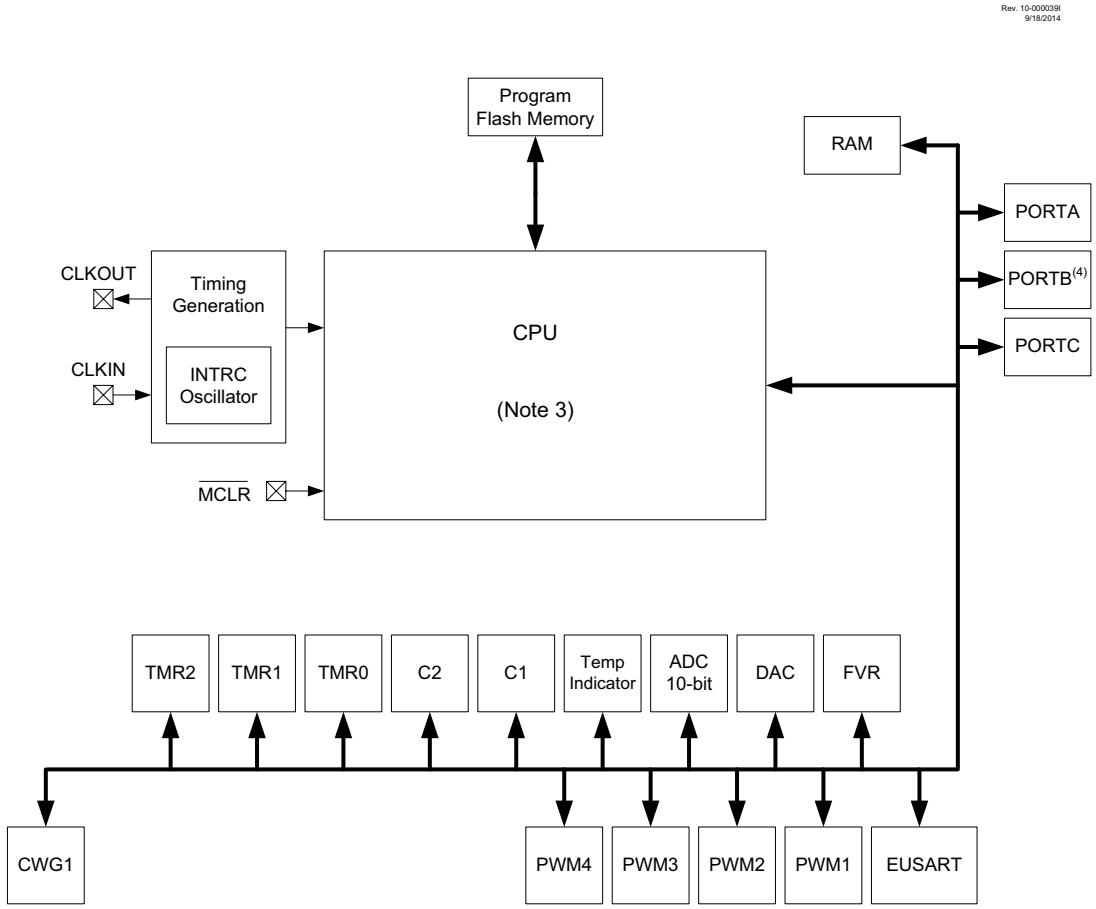
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	LINbus, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	12
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 8x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-UQFN Exposed Pad
Supplier Device Package	16-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1574t-i-jq

TABLE 2: PACKAGES

Packages	PDIP	SOIC	TSSOP	SSOP	UQFN
PIC16(L)F1574	●	●	●		●
PIC16(L)F1575	●	●	●		●
PIC16(L)F1578	●	●		●	●
PIC16(L)F1579	●	●		●	●

Note: Pin details are subject to change.

FIGURE 1-1: PIC16(L)F1574/5/8/9 BLOCK DIAGRAM



Note 1: See applicable chapters for more information on peripherals.
2: See Table 1-1 for peripherals available on specific devices.
3: See Figure 2-1.
4: PIC16(L)F1578/9 only.

4.7 Register Definitions: Device ID

REGISTER 4-3: DEVICEID: DEVICE ID REGISTER(1)

R	R	R	R	R	R
DEV<13:8>					
bit 13					bit 8

R	R	R	R	R	R	R	R
DEV<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit		
'0' = Bit is cleared	'1' = Bit is set	x = Bit is unknown

bit 13-0 **DEV<13:0>:** Device ID bits
Refer to Table 4-1 to determine what these bits will read on which device. A value of 3FFFh is invalid.

Note 1: This location cannot be written.

REGISTER 4-4: REVISIONID: REVISION ID REGISTER(1)

R	R	R	R	R	R
REV<13:8>					
bit 13					bit 8

R	R	R	R	R	R	R	R
REV<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit		
'0' = Bit is cleared	'1' = Bit is set	x = Bit is unknown

bit 13-0 **REV<13:0>:** Revision ID bits
These bits are used to identify the device revision.

Note 1: This location cannot be written.

TABLE 4-1: DEVICE ID VALUES

DEVICE	Device ID	Revision ID
PIC16F1574	3000h	2xxxh
PIC16F1575	3001h	2xxxh
PIC16F1578	3002h	2xxxh
PIC16F1579	3003h	2xxxh
PIC16LF1574	3004h	2xxxh
PIC16LF1575	3005h	2xxxh
PIC16LF1578	3006h	2xxxh
PIC16LF1579	3007h	2xxxh

FIGURE 5-3: INTERNAL OSCILLATOR SWITCH TIMING

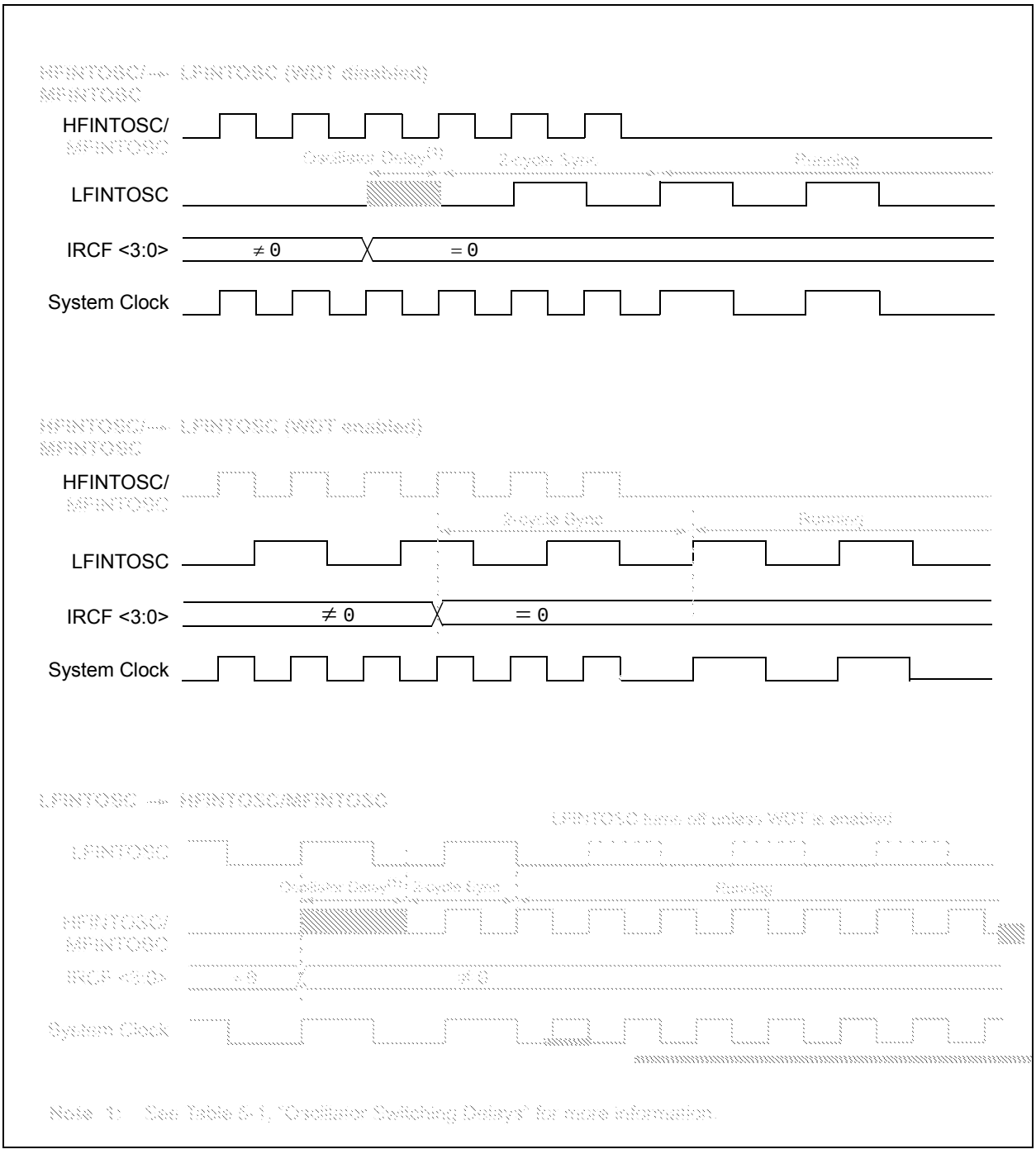
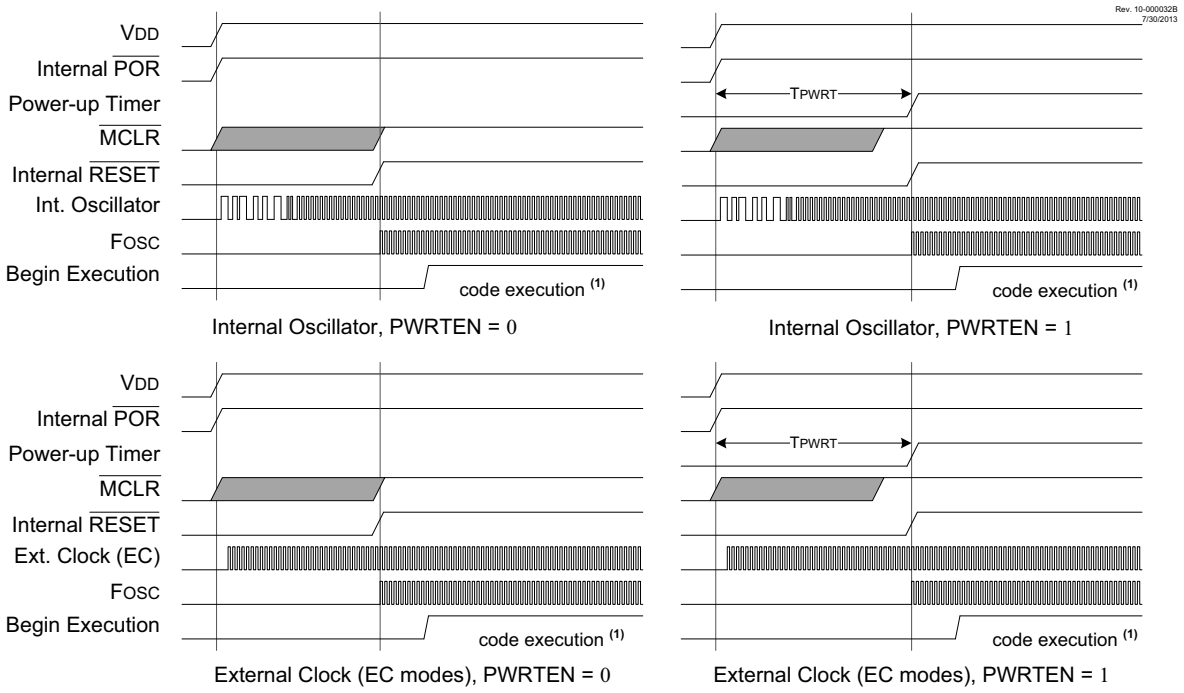


FIGURE 6-3: RESET START-UP SEQUENCE



Note 1: Code execution begins 10 FOSC cycles after the FOSC clock is released.

9.1 Independent Clock Source

The WDT derives its time base from the 31 kHz LFINTOSC internal oscillator. Time intervals in this chapter are based on a nominal interval of 1 ms. See **Section 27.0 "Electrical Specifications"** for the LFINTOSC tolerances.

9.2 WDT Operating Modes

The Watchdog Timer module has four operating modes controlled by the WDTE<1:0> bits in Configuration Words. See Table 9-1.

9.2.1 WDT IS ALWAYS ON

When the WDTE bits of Configuration Words are set to '11', the WDT is always on.

WDT protection is active during Sleep.

9.2.2 WDT IS OFF IN SLEEP

When the WDTE bits of Configuration Words are set to '10', the WDT is on, except in Sleep.

WDT protection is not active during Sleep.

9.2.3 WDT CONTROLLED BY SOFTWARE

When the WDTE bits of Configuration Words are set to '01', the WDT is controlled by the SWDTEN bit of the WDTCON register.

WDT protection is unchanged by Sleep. See Table 9-1 for more details.

TABLE 9-1: WDT OPERATING MODES

WDTE<1:0>	SWDTEN	Device Mode	WDT Mode
11	X	X	Active
10	X	Awake	Active
		Sleep	Disabled
01	1	X	Active
	0	X	Disabled
00	X	X	Disabled

9.3 Time-Out Period

The WDTPS bits of the WDTCON register set the time-out period from 1 ms to 256 seconds (nominal). After a Reset, the default time-out period is two seconds.

9.4 Clearing the WDT

The WDT is cleared when any of the following conditions occur:

- Any Reset
- CLRWDT instruction is executed
- Device enters Sleep
- Device wakes up from Sleep
- Oscillator fail
- WDT is disabled
- Oscillator Start-up Timer (OST) is running

See Table 9-2 for more information.

9.5 Operation During Sleep

When the device enters Sleep, the WDT is cleared. If the WDT is enabled during Sleep, the WDT resumes counting. When the device exits Sleep, the WDT is cleared again.

The WDT remains clear until the OST, if enabled, completes. See **Section 5.0 "Oscillator Module"** for more information on the OST.

When a WDT time-out occurs while the device is in Sleep, no Reset is generated. Instead, the device wakes up and resumes operation. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register are changed to indicate the event. The $\overline{RWDT}$ bit in the PCON register can also be used. See **Section 3.0 "Memory Organization"** for more information.

TABLE 9-2: WDT CLEARING CONDITIONS

Conditions	WDT
WDTE<1:0> = 00	Cleared
WDTE<1:0> = 01 and SWDTEN = 0	
WDTE<1:0> = 10 and enter Sleep	
CLRWDT Command	
Oscillator Fail Detected	
Exit Sleep + System Clock = EXTRC, INTOSC, EXTCLK	
Change INTOSC divider (IRCF bits)	Unaffected

TABLE 13-1: SUMMARY OF REGISTERS ASSOCIATED WITH INTERRUPT-ON-CHANGE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	—	—	—	ANSA4	—	ANSA2	ANSA1	ANSA0	121
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	86
IOCAF	—	—	IOCAF5	IOCAF4	IOCAF3	IOCAF2	IOCAF1	IOCAF0	143
IOCAN	—	—	IOCAN5	IOCAN4	IOCAN3	IOCAN2	IOCAN1	IOCAN0	143
IOCAP	—	—	IOCAP5	IOCAP4	IOCAP3	IOCAP2	IOCAP1	IOCAP0	143
IOCBP(2)	IOCBP7	IOCBP6	IOCBP5	IOCBP4	—	—	—	—	144
IOCBN(2)	IOCBN7	IOCBN6	IOCBN5	IOCBN4	—	—	—	—	144
IOCBF(2)	IOCBF7	IOCBF6	IOCBF5	IOCBF4	—	—	—	—	144
IOCCP	IOCCP7(2)	IOCCP6(2)	IOCCP5	IOCCP4	IOCCP3	IOCCP2	IOCCP1	IOCCP0	145
IOCCN	IOCCN7(2)	IOCCN6(2)	IOCCN5	IOCCN4	IOCCN3	IOCCN2	IOCCN1	IOCCN0	145
IOCCF	IOCCF7(2)	IOCCF6(2)	IOCCF5	IOCCF4	IOCCF3	IOCCF2	IOCCF1	IOCCF0	145
TRISA	—	—	TRISA5	TRISA4	—(1)	TRISA2	TRISA1	TRISA0	120
TRISC	TRISC7(2)	TRISC7(2)	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	131

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by interrupt-on-change.

Note 1: Unimplemented, read as '1'.

2: PIC16(L)F1578/9 only.

14.3 Register Definitions: FVR Control

REGISTER 14-1: FVRCON: FIXED VOLTAGE REFERENCE CONTROL REGISTER

R/W-0/0	R-q/q	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
FVREN(1)	FVRRDY(2)	TSEN(3)	TSRNG(3)	CDAFVR<1:0>(1)		ADFVR<1:0>(1)	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7 **FVREN:** Fixed Voltage Reference Enable bit(1)
1 = Fixed Voltage Reference is enabled
0 = Fixed Voltage Reference is disabled

bit 6 **FVRRDY:** Fixed Voltage Reference Ready Flag bit(2)
1 = Fixed Voltage Reference output is ready for use
0 = Fixed Voltage Reference output is not ready or not enabled

bit 5 **TSEN:** Temperature Indicator Enable bit(3)
1 = Temperature Indicator is enabled
0 = Temperature Indicator is disabled

bit 4 **TSRNG:** Temperature Indicator Range Selection bit(3)
1 = $V_{OUT} = V_{DD} - 4V_T$ (High Range)
0 = $V_{OUT} = V_{DD} - 2V_T$ (Low Range)

bit 3-2 **CDAFVR<1:0>:** Comparator FVR Buffer Gain Selection bits(1)
11 = Comparator FVR Buffer Gain is 4x, with output $V_{CDAFVR} = 4x\ V_{FVR}$(4)
10 = Comparator FVR Buffer Gain is 2x, with output $V_{CDAFVR} = 2x\ V_{FVR}$(4)
01 = Comparator FVR Buffer Gain is 1x, with output $V_{CDAFVR} = 1x\ V_{FVR}$
00 = Comparator FVR Buffer is off

bit 1-0 **ADFVR<1:0>:** ADC FVR Buffer Gain Selection bit(1)
11 = ADC FVR Buffer Gain is 4x, with output $V_{ADFVR} = 4x\ V_{FVR}$(4)
10 = ADC FVR Buffer Gain is 2x, with output $V_{ADFVR} = 2x\ V_{FVR}$(4)
01 = ADC FVR Buffer Gain is 1x, with output $V_{ADFVR} = 1x\ V_{FVR}$
00 = ADC FVR Buffer is off

Note 1: To minimize current consumption when the FVR is disabled, the FVR buffers should be turned off by clearing the Buffer Gain Selection bits.
2: FVRRDY is always '1' for the PIC16F1574/5/8/9 devices.
3: See **Section 15.0 "Temperature Indicator Module"** for additional information.
4: Fixed Voltage Reference output cannot exceed V_{DD}.

TABLE 14-2: SUMMARY OF REGISTERS ASSOCIATED WITH THE FIXED VOLTAGE REFERENCE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	CDAFVR>1:0>		ADFVR<1:0>		149

Legend: Shaded cells are unused by the Fixed Voltage Reference module.

16.2.6 ADC CONVERSION PROCEDURE

This is an example procedure for using the ADC to perform an Analog-to-Digital conversion:

1. Configure Port:
   - Disable pin output driver (Refer to the TRIS register)
   - Configure pin as analog (Refer to the ANSEL register)
   - Disable weak pull-ups either globally (Refer to the OPTION_REG register) or individually (Refer to the appropriate WPUx register)
2. Configure the ADC module:
   - Select ADC conversion clock
   - Configure voltage reference
   - Select ADC input channel
   - Turn on ADC module
3. Configure ADC interrupt (optional):
   - Clear ADC interrupt flag
   - Enable ADC interrupt
   - Enable peripheral interrupt
   - Enable global interrupt(1)
4. Wait the required acquisition time(2).
5. Start conversion by setting the GO/$\overline{\text{DONE}}$ bit.
6. Wait for ADC conversion to complete by one of the following:
   - Polling the GO/$\overline{\text{DONE}}$ bit
   - Waiting for the ADC interrupt (interrupts enabled)
7. Read ADC Result.
8. Clear the ADC interrupt flag (required if interrupt is enabled).

Note 1: The global interrupt can be disabled if the user is attempting to wake-up from Sleep and resume in-line code execution.

2: Refer to **Section 16.4 "ADC Acquisition Requirements"**.

EXAMPLE 16-1: ADC CONVERSION

```
;This code block configures the ADC
;for polling, Vdd and Vss references, FRC
;oscillator and AN0 input.
;
;Conversion start & polling for completion
; are included.
;
BANKSEL   ADCON1       ;
MOVLW     B'11110000'  ;Right justify, FRC
                       ;oscillator
MOVWF     ADCON1       ;Vdd and Vss Vref+
BANKSEL   TRISA        ;
BSF       TRISA,0      ;Set RA0 to input
BANKSEL   ANSEL        ;
BSF       ANSEL,0      ;Set RA0 to analog
BANKSEL   WPUA
BCF       WPUA,0       ;Disable weak
                       ;pull-up on RA0
BANKSEL   ADCON0       ;
MOVLW     B'00000001'  ;Select channel AN0
MOVWF     ADCON0       ;Turn ADC On
CALL      SampleTime   ;Acquisiton delay
BSF       ADCON0,ADGO  ;Start conversion
BTFSC     ADCON0,ADGO  ;Is conversion done?
GOTO      $-1          ;No, test again
BANKSEL   ADRESH       ;
MOVF      ADRESH,W     ;Read upper 2 bits
MOVWF     RESULTHI     ;store in GPR space
BANKSEL   ADRESL       ;
MOVF      ADRESL,W     ;Read lower 8 bits
MOVWF     RESULTLO     ;Store in GPR space
```

16.4 ADC Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 16-5. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), refer to Figure 16-5. **The maximum recommended impedance for analog sources is 10 kΩ.** As the source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an ADC acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 16-1 may be used. This equation assumes that 1/2 LSb error is used (1,024 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 16-1: ACQUISITION TIME EXAMPLE

Assumptions: $Temperature = 50°C$ *and external impedance of* $10k\Omega$ $5.0V$ V_{DD}

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$
$$= 2\mu s + T_C + [(Temperature - 25°C)(0.05\mu s/°C)]$$

The value for T_C *can be approximated with the following equations:*

$$V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) = V_{CHOLD} \quad ;[1]\ V_{CHOLD}\ \text{charged to within 1/2 lsb}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{CHOLD} \quad ;[2]\ V_{CHOLD}\ \text{charge response to}\ V_{APPLIED}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) \quad ;\text{combining [1] and [2]}$$

Note: Where n = number of bits of the ADC.

Solving for T_C*:*

$$T_C = -C_{HOLD}(R_{IC} + R_{SS} + R_S)\ ln(1/2047)$$
$$= -12.5pF(1k\Omega + 7k\Omega + 10k\Omega)\ ln(0.0004885)$$
$$= 1.715\mu s$$

Therefore:

$$T_{ACQ} = 2\mu s + 1.715\mu s + [(50°C - 25°C)(0.05\mu s/°C)]$$
$$= 4.96\mu s$$

Note 1: The reference voltage (VRPOS) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

20.6 Timer1 Interrupt

The Timer1 register pair (TMR1H:TMR1L) increments to FFFFh and rolls over to 0000h. When Timer1 rolls over, the Timer1 interrupt flag bit of the PIR1 register is set. To enable the interrupt on rollover, you must set these bits:

- TMR1ON bit of the T1CON register
- TMR1IE bit of the PIE1 register
- PEIE bit of the INTCON register
- GIE bit of the INTCON register

The interrupt is cleared by clearing the TMR1IF bit in the Interrupt Service Routine.

Note:	The TMR1H:TMR1L register pair and the TMR1IF bit should be cleared before enabling interrupts.

20.7 Timer1 Operation During Sleep

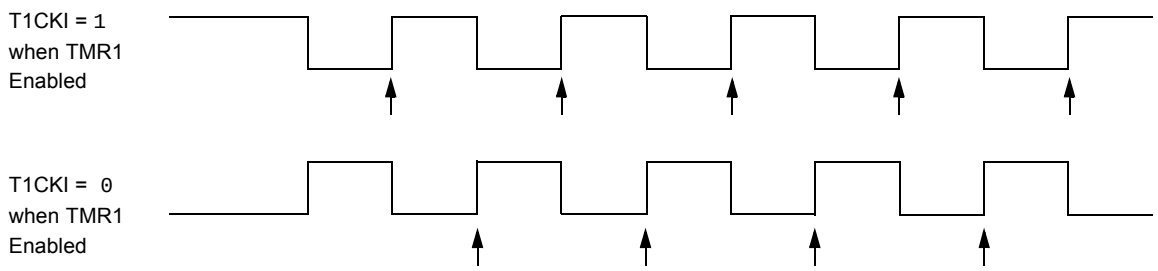
Timer1 can only operate during Sleep when setup in Asynchronous Counter mode. In this mode, an external crystal or clock source can be used to increment the counter. To set up the timer to wake the device:

- TMR1ON bit of the T1CON register must be set
- TMR1IE bit of the PIE1 register must be set
- PEIE bit of the INTCON register must be set
- $\overline{\text{T1SYNC}}$ bit of the T1CON register must be set
- TMR1CS bits of the T1CON register must be configured

The device will wake-up on an overflow and execute the next instructions. If the GIE bit of the INTCON register is set, the device will call the Interrupt Service Routine.

Timer1 oscillator will continue to operate in Sleep regardless of the $\overline{\text{T1SYNC}}$ bit setting.

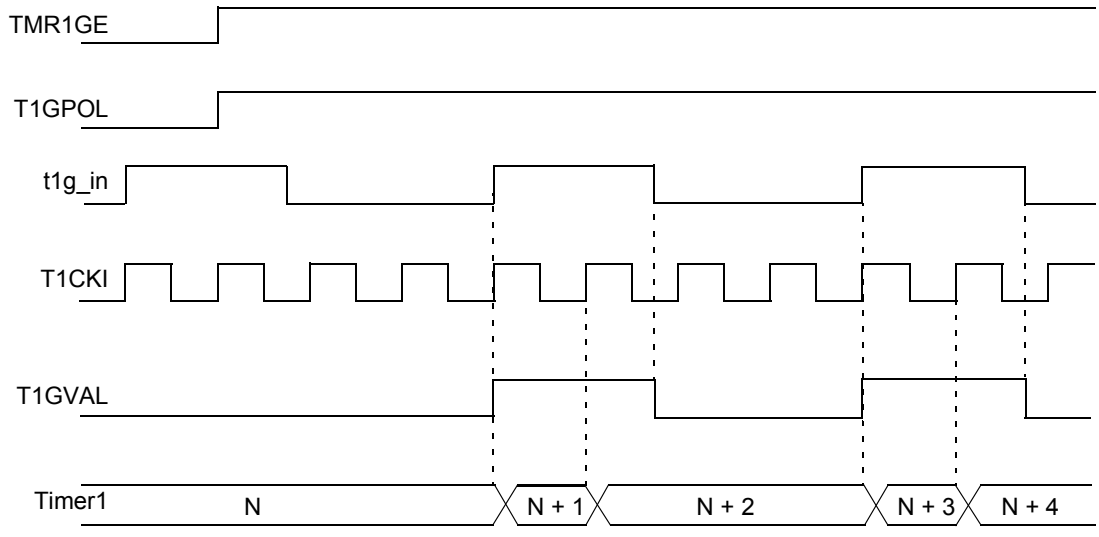
FIGURE 20-2: TIMER1 INCREMENTING EDGE



Note 1: Arrows indicate counter increments.

2: In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge of the clock.

FIGURE 20-3: TIMER1 GATE ENABLE MODE



22.4 EUSART Baud Rate Generator (BRG)

The Baud Rate Generator (BRG) is an 8-bit or 16-bit timer that is dedicated to the support of both the asynchronous and synchronous EUSART operation. By default, the BRG operates in 8-bit mode. Setting the BRG16 bit of the BAUDCON register selects 16-bit mode.

The SPBRGH, SPBRGL register pair determines the period of the free running baud rate timer. In Asynchronous mode the multiplier of the baud rate period is determined by both the BRGH bit of the TXSTA register and the BRG16 bit of the BAUDCON register. In Synchronous mode, the BRGH bit is ignored.

Table 22-3 contains the formulas for determining the baud rate. Example 22-1 provides a sample calculation for determining the baud rate and baud rate error.

Typical baud rates and error values for various Asynchronous modes have been computed for your convenience and are shown in Table 22-3. It may be advantageous to use the high baud rate (BRGH = 1), or the 16-bit BRG (BRG16 = 1) to reduce the baud rate error. The 16-bit BRG mode is used to achieve slow baud rates for fast oscillator frequencies.

Writing a new value to the SPBRGH, SPBRGL register pair causes the BRG timer to be reset (or cleared). This ensures that the BRG does not wait for a timer overflow before outputting the new baud rate.

If the system clock is changed during an active receive operation, a receive error or data loss may result. To avoid this problem, check the status of the RCIDL bit to make sure that the receive operation is idle before changing the system clock.

EXAMPLE 22-1: CALCULATING BAUD RATE ERROR

For a device with FOSC of 16 MHz, desired baud rate of 9600, Asynchronous mode, 8-bit BRG:

$$Desired\ Baud\ Rate = \frac{FOSC}{64([SPBRGH:SPBRGL] + 1)}$$

Solving for SPBRGH:SPBRGL:

$$X = \frac{\frac{FOSC}{Desired\ Baud\ Rate}}{64} - 1$$

$$= \frac{\frac{16000000}{9600}}{64} - 1$$

$$= [25.042] = 25$$

$$Calculated\ Baud\ Rate = \frac{16000000}{64(25 + 1)}$$

$$= 9615$$

$$Error = \frac{Calc.\ Baud\ Rate - Desired\ Baud\ Rate}{Desired\ Baud\ Rate}$$

$$= \frac{(9615 - 9600)}{9600} = 0.16\%$$

REGISTER 23-15: PWMxTMRH: PWMx TIMER HIGH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
TMR<15:8>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **TMR<15:8>**: PWM Timer High bits
Upper eight bits of PWM timer counter

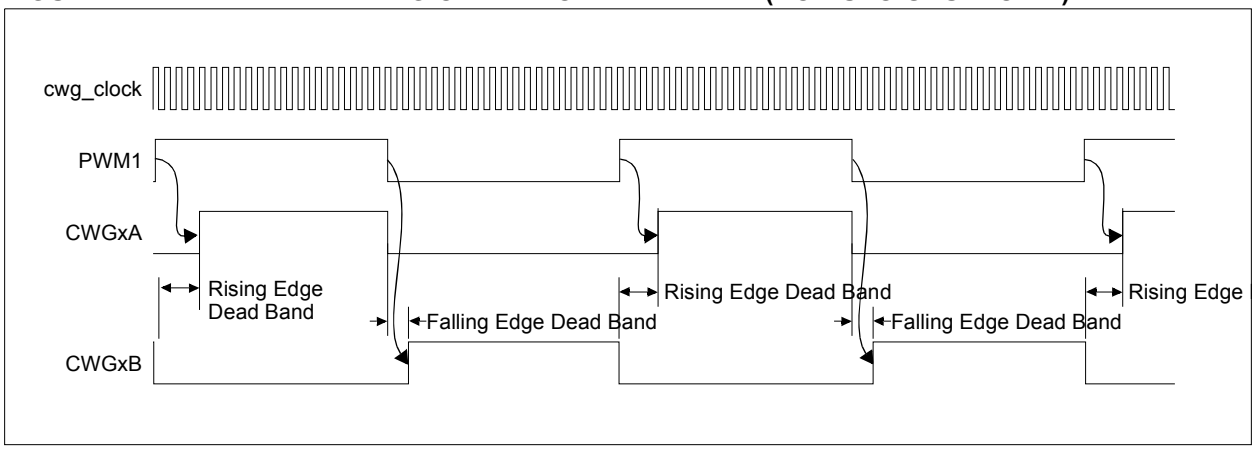
REGISTER 23-16: PWMxTMRL: PWMx TIMER LOW REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
TMR<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **TMR<7:0>**: PWM Timer Low bits
Lower eight bits of PWM timer counter

FIGURE 24-2: TYPICAL CWG OPERATION WITH PWM1 (NO AUTO-SHUTDOWN)



24.5 Dead-Band Control

Dead-band control provides for non-overlapping output signals to prevent shoot-through current in power switches. The CWG contains two 6-bit dead-band counters. One dead-band counter is used for the rising edge of the input source control. The other is used for the falling edge of the input source control.

Dead band is timed by counting CWG clock periods from zero up to the value in the rising or falling dead-band counter registers. See CWGxDBR and CWGxDBF registers (Register 24-4 and Register 24-5, respectively).

24.6 Rising Edge Dead Band

The rising edge dead-band delays the turn-on of the CWGxA output from when the CWGxB output is turned off. The rising edge dead-band time starts when the rising edge of the input source signal goes true. When this happens, the CWGxB output is immediately turned off and the rising edge dead-band delay time starts. When the rising edge dead-band delay time is reached, the CWGxA output is turned on.

The CWGxDBR register sets the duration of the dead-band interval on the rising edge of the input source signal. This duration is from 0 to 64 counts of dead band.

Dead band is always counted off the edge on the input source signal. A count of 0 (zero), indicates that no dead band is present.

If the input source signal is not present for enough time for the count to be completed, no output will be seen on the respective output.

24.7 Falling Edge Dead Band

The falling edge dead band delays the turn-on of the CWGxB output from when the CWGxA output is turned off. The falling edge dead-band time starts when the falling edge of the input source goes true. When this happens, the CWGxA output is immediately turned off and the falling edge dead-band delay time starts. When the falling edge dead-band delay time is reached, the CWGxB output is turned on.

The CWGxDBF register sets the duration of the dead-band interval on the falling edge of the input source signal. This duration is from 0 to 64 counts of dead band.

Dead band is always counted off the edge on the input source signal. A count of 0 (zero), indicates that no dead band is present.

If the input source signal is not present for enough time for the count to be completed, no output will be seen on the respective output.

Refer to Figure 24-3 and Figure 24-4 for examples.

SWAPF **Swap Nibbles in f**

Syntax:	[*label*] SWAPF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f<3:0>) → (destination<7:4>), (f<7:4>) → (destination<3:0>)
Status Affected:	None
Description:	The upper and lower nibbles of register 'f' are exchanged. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed in register 'f'.

TRIS **Load TRIS Register with W**

Syntax:	[*label*] TRIS f
Operands:	$5 \le f \le 7$
Operation:	(W) → TRIS register 'f'
Status Affected:	None
Description:	Move data from W register to TRIS register. When 'f' = 5, TRISA is loaded. When 'f' = 6, TRISB is loaded. When 'f' = 7, TRISC is loaded.

XORLW **Exclusive OR literal with W**

Syntax:	[*label*] XORLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .XOR. k → (W)
Status Affected:	Z
Description:	The contents of the W register are XOR'ed with the 8-bit literal 'k'. The result is placed in the W register.

XORWF **Exclusive OR W with f**

Syntax:	[*label*] XORWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) .XOR. (f) → (destination)
Status Affected:	Z
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

TABLE 27-3: POWER-DOWN CURRENTS (I_{PD})(1,2) (CONTINUED)

PIC16LF1574/5/8/9		Operating Conditions: (unless otherwise stated) Low-Power Sleep Mode						
PIC16F1574/5/8/9		Low-Power Sleep Mode, VREGPM = 1						
Param. No.	Device Characteristics	Min.	Typ†	Max. +85°C	Max. +125°C	Units	Conditions	
							V_{DD}	Note
D027		—	5	22	25	µA	1.8	Comparator, CxSP = 0
		—	5	23	27	µA	3.0	
D027		—	15	23	25	µA	2.3	Comparator, CxSP = 0
		—	17	27	29	µA	3.0	
		—	19	28	30	µA	5.0	
D028A		—	23	41	42	µA	1.8	Comparator, Normal Power, CxSP = 1 **(Note 1)**
		—	25	42	44	µA	3.0	
D028A		—	33	55	56	µA	2.3	Comparator, Normal Power, CxSP = 1 VREGPM = 1 **(Note 1)**
		—	34	59	60	µA	3.0	
		—	36	60	61	µA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral Δ current can be determined by subtracting the base I_{PD} current from this limit. Max. values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to V_{SS}.

3: ADC clock source is FRC.

TABLE 27-6: THERMAL CHARACTERISTICS

Standard Operating Conditions (unless otherwise stated)					
Param. No.	**Sym.**	**Characteristic**	**Typ.**	**Units**	**Conditions**
TH01	θ_{JA}	Thermal Resistance Junction to Ambient	70	°C/W	14-pin PDIP package
			95.3	°C/W	14-pin SOIC package
			100	°C/W	14-pin TSSOP package
			31.8	°C/W	16-pin UQFN 4x4mm package
			62.2	°C/W	20-pin PDIP package
			77.7	°C/W	20-pin SOIC package
			87.3	°C/W	20-pin SSOP package
			32.8	°C/W	20-pin UQFN 4x4mm package
TH02	θ_{JC}	Thermal Resistance Junction to Case	32.75	°C/W	14-pin PDIP package
			31	°C/W	14-pin SOIC package
			24.4	°C/W	14-pin TSSOP package
			24.4	°C/W	16-pin UQFN 4x4mm package
			27.5	°C/W	20-pin PDIP package
			23.1	°C/W	20-pin SOIC package
			31.1	°C/W	20-pin SSOP package
			27.4	°C/W	20-pin UQFN 4x4mm package
TH03	T_{JMAX}	Maximum Junction Temperature	150	°C	
TH04	PD	Power Dissipation	—	W	$PD = P_{INTERNAL} + P_{I/O}$
TH05	$P_{INTERNAL}$	Internal Power Dissipation	—	W	$P_{INTERNAL} = I_{DD} \times V_{DD}$ (1)
TH06	$P_{I/O}$	I/O Power Dissipation	—	W	$P_{I/O} = \Sigma (I_{OL} * V_{OL}) + \Sigma (I_{OH} * (V_{DD} - V_{OH}))$
TH07	P_{DER}	Derated Power	—	W	$P_{DER} = PD_{MAX} (T_J - T_A)/\theta_{JA}$ (2)

Note 1: I_{DD} is current to run the chip alone without driving any load on the output pins.

2: T_A = Ambient Temperature; T_J = Junction Temperature

27.4 AC Characteristics

Timing Parameter Symbology has been created with one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

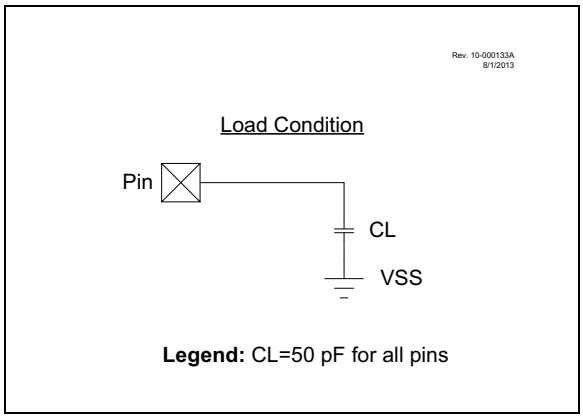
Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	CLKIN
ck	CLKOUT	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDIx	sc	SCKx
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O PORT	t1	T1CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-impedance)	V	Valid
L	Low	Z	High-impedance

FIGURE 27-4: LOAD CONDITIONS



Legend: CL=50 pF for all pins

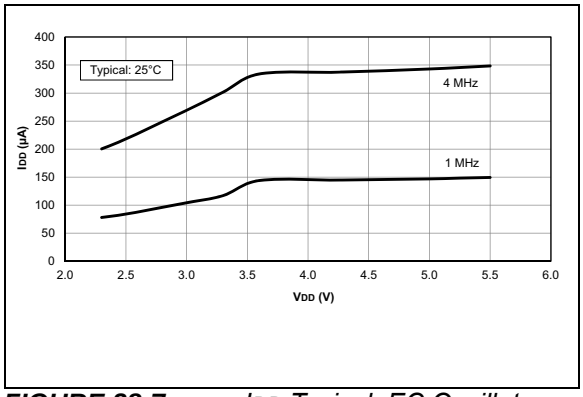


FIGURE 28-7: *IDD Typical, EC Oscillator, Medium Power Mode, PIC16F1574/5/8/9 Only.*

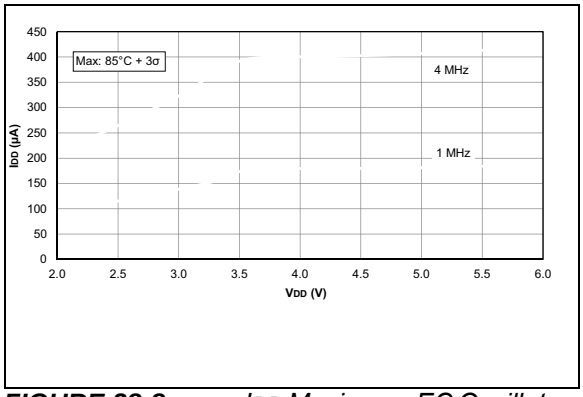


FIGURE 28-8: *IDD Maximum, EC Oscillator, Medium Power Mode, PIC16F1574/5/8/9 Only.*

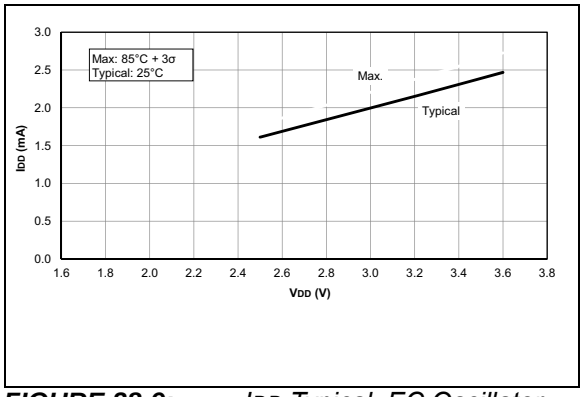


FIGURE 28-9: *IDD Typical, EC Oscillator, High-Power Mode, FOSC = 32 kHz, PIC16LF1574/5/8/9 Only.*

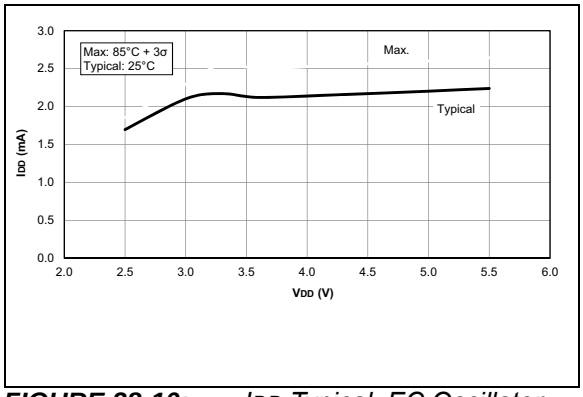


FIGURE 28-10: *IDD Typical, EC Oscillator, High-Power Mode, FOSC = 32 kHz, PIC16F1574/5/8/9 Only.*

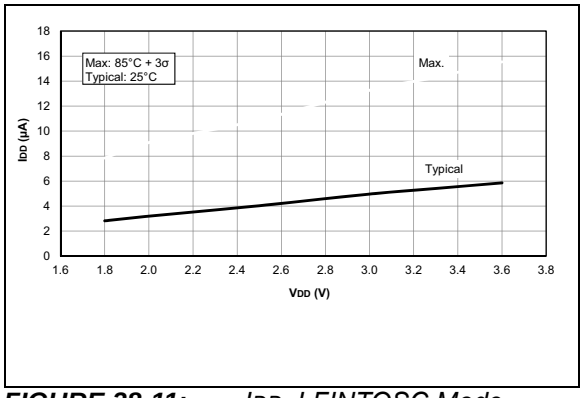


FIGURE 28-11: *IDD, LFINTOSC Mode, FOSC = 31 kHz, PIC16LF1574/5/8/9 Only.*

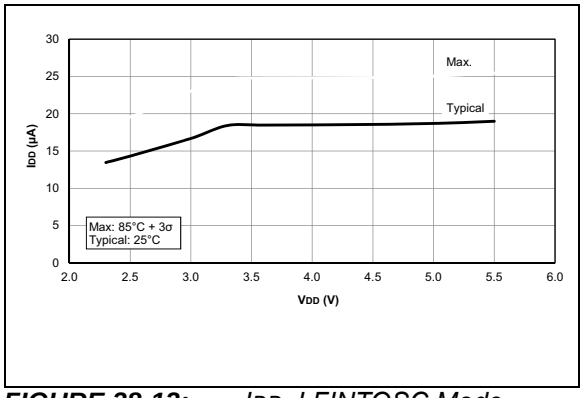


FIGURE 28-12: *IDD, LFINTOSC Mode, FOSC = 31 kHz, PIC16F1574/5/8/9 Only.*

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